

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:

NEW ASSIGNMENT

NATURE OF CONVEYANCE:

ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Claudius Feger	06/06/2011
Mark H. McLeod	06/02/2011
Jae-Woong Nah	06/06/2011
Eric D. Perfecto	06/06/2011

RECEIVING PARTY DATA

Name:	INTERNATIONAL BUSINESS MACHINES CORPORATION
Street Address:	New Orchard Road
City:	Armonk
State/Country:	NEW YORK
Postal Code:	10504

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13154412

CORRESPONDENCE DATA

Fax Number: (203)769-5706

*Correspondence will be sent via US Mail when the fax attempt is unsuccessful.*

Phone: 203 433 3157

Email: docket@oeklaw.com

Correspondent Name: Otterstedt, Ellenbogen & Kammer, LLP

Address Line 1: P.O. Box 381

Address Line 4: Cos Cob, CONNECTICUT 06807-0381

ATTORNEY DOCKET NUMBER:

YOR920110167US1

NAME OF SUBMITTER:

Paul J. Otterstedt

Total Attachments: 8

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**ASSIGNMENT**

Whereas, the undersigned Inventor(s) has/have made certain inventions, improvements, and discoveries (herein referred to as the "Invention") in:

Title of the Invention: **INJECTION MOLDED SOLDER PROCESS FOR FORMING SOLDER BUMPS ON SUBSTRATES**

and further identified by the IBM Docket Number provided above in the header of this Assignment, for which an application for a United States Patent was executed concurrently herewith or was filed having:

Application No.: 13/154,412 (insert series code /serial number here if/when available)


Whereas, International Business Machines Corporation, a corporation of New York having a place of business at Armonk, New York (herein referred to as "IBM"), desires to acquire, and each undersigned Inventor desires to grant to IBM, the entire worldwide right, title, and interest in and to the Invention and in and to any and all patent applications and patents directed thereto;

Now, therefore, for good and valuable consideration, the receipt and sufficiency thereof being hereby acknowledged, each undersigned Inventor ("ASSIGNOR") hereby sells, assigns, and otherwise transfers to IBM (the "ASSIGNEE"), its successors, legal representatives, and assigns, the entire worldwide right, title, and interest in and to the Invention, the above-identified United States patent application, and any and all other patent applications and patents for the Invention which may be applied for or granted therefor in the United States and in all foreign countries and jurisdictions, including all divisions, continuations, reissues, reexaminations, renewals, extensions, counterparts, substitutes, and extensions thereof, and all rights of priority resulting from the filing of such applications and granting of such patents. In addition, each undersigned Inventor hereby authorizes and requests the Director of the United States Patent and Trademark Office to issue any United States Patent, and foreign patent authorities to issue any foreign patent, granted for the Invention, to IBM, its successors, legal representatives, and assigns, the entire worldwide right, title, and interest in and to the same to be held and enjoyed by IBM, its successors, legal representatives, and assigns to the full end of the terms for which any and all such patents may be granted, as fully and entirely as would have been held and enjoyed by the undersigned had this Assignment not been made; and each undersigned Inventor agrees to execute any and all documents and instruments and perform all lawful acts reasonably related to recording this Assignment or perfecting title to the Invention and all related patents and applications, in IBM, its successors, legal representatives, and assigns, whenever requested by IBM, its successors, legal representatives, or assigns.

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[Inventor Signature Page(s) Follows]

Executed by Inventor 1

Signature:  Date: 6/6/2011  
Claudius Feger

Executed by Inventor 2

Signature: \_\_\_\_\_ Date: \_\_\_\_\_  
Mark H. McLeod

Executed by Inventor 3

Signature: \_\_\_\_\_ Date: \_\_\_\_\_  
Jae-Woong Nah

Executed by Inventor 4

Signature: \_\_\_\_\_ Date: \_\_\_\_\_  
Eric D. Perfecto

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Claudius Feger

Executed by Inventor 2

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Signature: Mark H. McLeod Date: 6/2/2011  
Mark H. McLeod

Executed by Inventor 3

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Signature: \_\_\_\_\_ Date: \_\_\_\_\_  
Jae-Woong Nah

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